

Chip Scale

REVIEW®

EDITORIAL CALENDAR

Eight issues in 2004

Issue	Emphasis	Special Reports	Vendor Directories	Tutorial	Show Distribution [*]  Space Close (Materials)  Mailing Date
January-February	<ul style="list-style-type: none"> Dispensing, encapsulation and underfilling MEMS Thermal management 	<ul style="list-style-type: none"> The dispensing equipment selection conundrum: How to buy just what you need without going overboard New frontiers in MEMS fabrication and technology innovations Heating up: The role of thermal management in successful package assembly 	<ul style="list-style-type: none"> Dispensing equipment Encapsulants 	<ul style="list-style-type: none"> Encapsulants 	<ul style="list-style-type: none"> SEMICON Korea, Feb. 18-21, Seoul APEX, Feb. 24-26, Anaheim SEMICON China, March 17-19, Shanghai  Nov 22 (Nov 29)  Dec 20
March	<ul style="list-style-type: none"> IC assembly equipment Flip-chip packaging 	<ul style="list-style-type: none"> The renaissance in IC assembly equipment: Vendors ponder post-recession demands Flip-chip packaging: Meeting the challenges abound on the growth curve 	<ul style="list-style-type: none"> Flip-chip bonders Wire bonders 	<ul style="list-style-type: none"> Flip-chip technology 	<ul style="list-style-type: none"> BiTS Conference, March 7-10, Mesa, AZ  Jan 22 (Jan 29)  Feb 19
April	<ul style="list-style-type: none"> Test and burn-in sockets Burn-in ovens Final test trends 	<ul style="list-style-type: none"> Test sockets for gigahertz frequencies continue moving skyward! Key points in selecting burn-in ovens Final test: General purpose tools make way for more specialized gear 	<ul style="list-style-type: none"> Test and burn-in sockets Burn-in ovens 	<ul style="list-style-type: none"> Burn-in 	<ul style="list-style-type: none"> SEMICON Europa, April 19-23, Munich  Feb 21 (Feb 28)  Mar 23
May-June	<ul style="list-style-type: none"> IC packaging foundries Stencil printing trends 	<ul style="list-style-type: none"> After two dry years, IC assemblers unwrap recovery plans How to select the right stencil printer for your application 	<ul style="list-style-type: none"> IC packaging foundries Stencil printers 	<ul style="list-style-type: none"> Stencil printing 	<ul style="list-style-type: none"> ECTC, June 1-4, Las Vegas SMT/Hybrid/ Packaging 2004, June 15-17, Nuremberg, Germany  Mar 31 (Apr 7)  Apr 28
July	<ul style="list-style-type: none"> Wafer bumping Wafer-level packaging Lithography for IC packaging 	<ul style="list-style-type: none"> Wafer-bumping services: How to select the best A critical retrospective on wafer-level packaging Lithography tools for packaging: Defining the choices 	<ul style="list-style-type: none"> Wafer-bumping providers Lithography systems for packaging 	<ul style="list-style-type: none"> Wafer-level packaging 	<ul style="list-style-type: none"> SEMICON West (Final Manufacturing), July 14-16, San Jose  May 23 (May 30)  Jun 21
August-September	<ul style="list-style-type: none"> Solder Singulation Ball placement Wafer thinning Stacked-die packaging 	<ul style="list-style-type: none"> Where does lead-free solder go from here? The cutting edge: Complex devices spur new equipment and processes in the singulation equipment market Ball placement equipment options Impact of stacked-die packaging 	<ul style="list-style-type: none"> Singulation Solder ball placement Solder 	<ul style="list-style-type: none"> Singulation 	<ul style="list-style-type: none"> SEMICON Taiwan, Dates pending, Taipei KGD Conference, September 14-16, Napa, CA Assembly Technology Expo/SMTA International, September 26-30, Chicago  Jul 2 (Jul 12)  Aug 2
October	<ul style="list-style-type: none"> Inspection: AOI, AXI, acoustic Products for handling, packing and transporting finished ICs and wafers 	<ul style="list-style-type: none"> Why AOI systems are better for semiconductor package inspection Why AXI systems are better for semiconductor package inspection Safeguarding ICs and wafers in shipment 	<ul style="list-style-type: none"> Inspection systems Media for handling, storing and transporting finished ICs and wafers 	<ul style="list-style-type: none"> Inspection 	<ul style="list-style-type: none"> FSA Suppliers Expo, Dates pending, Santa Clara, CA IMAPS, November 16-18, Long Beach, CA  Aug 5 (Aug 12)  Sep 24
November-December	<ul style="list-style-type: none"> Socket update Cleaning systems 	<ul style="list-style-type: none"> What users say behind socket makers' backs: The good, the bad and the ugly 	<ul style="list-style-type: none"> Test and burn-in socket update Cleaning systems 	<ul style="list-style-type: none"> Socket selection 	<ul style="list-style-type: none"> SEMICON Japan, December 3-5, Chiba, Japan  Oct 4 (Oct 11)  Nov 1

^{*}Copies will also be distributed at all Arizona and California MEPTec luncheons.

Note: Due to circumstances beyond the publisher's control, show distribution cannot be guaranteed and is subject to change without notice.

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EXTRA! is Chip Scale Review's twice-monthly newsletter written and edited especially for Web visitors. EXTRA! fills in the gaps between Chip Scale Review's regular publication schedule with issues on the 15th and the last business day of the month.

Very user-friendly and attractive to read, within its 6-8 pages EXTRA! features in-depth news and analysis of current events in the semiconductor packaging and test industries prepared by our veteran editorial staff. Unlike most newsletters, photos are included with most articles for superior readability.

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Chip Scale
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7291 Coronado Drive, Suite 8 • San Jose, CA 95129
Tel: 408.996.7016 • Fax: 408.996.7871
ads@ChipScaleReview.com
www.ChipScaleReview.com